

L850-GL LTE Module

Perfect Wireless Experience

L850-GL LTE Module Technical Specifications

Product Features

- Chipset: Intel XMM7360
- LTE FDD: Band 1, 2, 3, 4, 5, 7, 8, 11, 12, 13, 17, 18, 19, 20, 21, 26, 28, 29, 30, 66
LTE TDD: B38/39/40/41
- UMTS: Band 1, 2, 4, 5, 8
- M.2: 30.0*42.0*2.3 mm
- Current Consumption: 6mA@sleep mode(DRX9)
- eSIM interface support
- Operating Voltage: 3.135V~4.4V, Typical 3.3V
- Operating Temperature: -20~+65°C
- Storage Temperature: -40~+85°C
- AT Command Set: 3GPP TS 27.007 and 27.005, proprietary FIBOCOM AT commands
- TX Power:
FDD&TDD LTE: 23dBm
WCDMA: 23.5dBm
- RX Sensitivity:
FDD&TDD LTE: -98dBm~102dBm

Data

- LTE FDD: 450Mbps DL, 50Mbps UL
LTE TDD: 347Mbps DL, 30Mbps UL
- UMTS: 385Kbps DL, 385Kbps UL
DC-HSUPA+: 42Mbps DL, 5.76Mbps UL

Interface

- USIM: 3V/1.8V
- PCIe
- BodySar
- USB2.0
- USB3.0(Non- Windows)
- BodySar
- Clock

Driver

- Win 10 / Android* / Linux*/Chorme OS

Note*: Planning

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